

Abstract of the Disclosure

5 A method and apparatus electrically coupling
input/output bond pads that are disposed proximate to one
another on a microelectronic device. The apparatus
includes a microelectronic device having at least two
conductive input/output bond pads electrically coupled to
an integrated circuit of the microelectronic device and
first and second conductive stud balls bonded to first
10 and second input/output pads, respectively, and a third
conductive stud ball bonded to the first and second
conductive stud balls. A wire bonding tool in "stud
ball" mode is utilized to bond the conductive stud balls.